

03/24/00

04-06-2000



101308241

U.S. PATENT AND TRADEMARK OFFICE

Case Docket No. 000385

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

RECORDATION FORM COVER SHEET  
PATENTS ONLY

To the Assistant Commissioner for Patents.  
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

**Shoichiro MATSUMOTO**

Additional name(s) of conveying party(ies) attached? NO

JC564 U.S. PTO  
09/537804  
03/24/00

2. Name and address of receiving party(ies):

Name: **SANYO ELECTRIC CO., LTD.**

Street Address: 5-5, Keihanhondori 2-chome, Moriguchi-shi,  
Osaka, Japan

09/537804

Additional name(s) & address(es) attached? NO

3. Nature of conveyance: **Assignment**

04/04/2000 LAMSHING 00000026 09537804

Execution Date (30.07.00) March 21, 2000

03 FC:581

4. Title: **SEMICONDUCTOR MEMORY DEVICE**

5. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: March 21, 2000

A. Patent Application No.(s)      B. Patent No.(s)

Additional numbers attached? NO

6. Name and address of party to whom correspondence concerning document should be mailed:

Name: Armstrong, Westerman, Hattori,  
McLeland & Naughton  
Suite 1000  
1725 K Street, N.W.  
Washington, D.C. 20006

7. Total number of applications and patents involved: 1

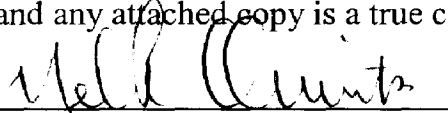
8. Total fee (37 CFR 3.41). . . . . \$ **40.00**

XX Check enclosed

9. Deposit Account No.: 01-2340

10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.



Date March 24, 2000

Mel R. Quintos  
Reg. No. 31,898

Total number of pages including cover sheet: 4

MRQ/yap

ATTORNEY DOCKET NO.

## ASSIGNMENT

Application No. \_\_\_\_\_

Filed \_\_\_\_\_

Insert Name(s)  
of Inventor(s)

➡ WHEREAS, Shoichiro MATSUMOTO

Insert Title  
of Invention

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in \_\_\_\_\_  
➡ Semiconductor Memory Device

for which an application for Letters Patent of the United States of America has been executed by the undersigned

Insert Date  
of Signing of  
Application

➡ on March 21, 2000; and

Insert Name  
of Assignee

➡ WHEREAS, Sanyo Electric Co., Ltd.

Insert Address  
of Assignee

➡ of 5-5, Keihanhondori 2-chome, Moriguchi-shi, Osaka, Japan

CHECK BOX  
IF APPROPRIATE

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and  
➡  in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

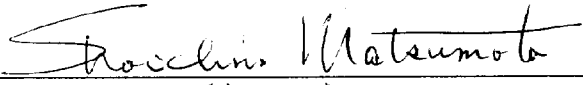
The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) the request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Armstrong, Westerman, Hattori, McLeland & Naughton the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

Date March 21, 2000 , Name of Inventor   
(signature) Shoichiro MATSUMOTO

Date \_\_\_\_\_ , Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_ , Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_ , Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_ , Name of Inventor \_\_\_\_\_  
(signature)

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(signature)

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(signature)

Date \_\_\_\_\_ , Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_ , Name of Inventor \_\_\_\_\_  
(signature)